



## Assembly and Packaging Japan TC Chapter Meeting Summary and Minutes

Japan Standards Spring 2017 Meetings  
Monday, March 13, 2017, 15:00–17:00  
SEMI Japan office, Tokyo, Japan

TC Chapter Announcements  
Next TC Chapter Meeting  
Monday, July 24, 2017 14:00–17:00 [JST]  
SEMI Japan office, Tokyo, Japan

### Table 1 Meeting Attendees

*Italics* indicate virtual participants

**Co-Chairs:** Kazunori Kato (AiT), Masahiro Tsuruya (iNEMI)

**SEMI Staff:** Chie Yanagisawa (SEMI Japan)

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
AIST	Shimamoto	Haruo	iNEMI	Tsuruya	Masahiro
AiT	Kato	Kazunori	Shin-Etsu Polymer	Suzuki	Hideki
Asahi Glass	Takahashi	Mamoru	Tokyo Seimitsu	Chiba	Kiyotaka
DISCO	Masuchi	Sumio	SEMI Japan	Yanagisawa	Chie

### Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

### Table 3 Committee Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	

### Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
None		

Note 1: **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

Note 2: **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

### Table 5 Activities Approved by the GCS prior to the Originating TC Chapter meeting

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			



**Table 6 Authorized Activities**

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	SC/TF/WG	Details
6154	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G10-96 (Reapproved 0811): "Standard Method for Mechanical Measurement of Plastic Package Leadframes" with non-conforming title change to "Test Method for Mechanical Measurement of Plastic Package Leadframes"
6148	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G18-96 (Reapproved 0811) "Standard for Integrated Circuit Leadframe Material Used in the Production of Etched Leadframes" with non-conforming title change to "Specification for Integrated Circuit Leadframe Material Used in the Production of Etched Leadframes"
6149	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G38-0996 (Reapproved 0811) "Test Method for Still- and Forced-Air Junction-to-Ambient Thermal Resistance Measurements of Integrated Circuit Packages"
6150	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G56-93 (Reapproved 0811) "Test Method for Measurement of Silver Plating Thickness"
6155	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G62-95 (Reapproved 0811) "Test Method for Silver Plating Quality"
6151	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G65-96 (Reapproved 0811) "Test Method for Evaluation of Leadframe Materials Used for L-Leaded (Gull Wing Type) Packages"
6156	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G70-0996 (Reapproved 0811) "Standard for Equipment and Leadframe Fixtures for Measurement of Plastic Package Leadframes" with non-conforming title change to "Specification for Equipment and Leadframe Fixtures for Measurement of Plastic Package Leadframes"
6167	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G73-0997 (Reapproved 0811) "Test Method for Pull Strength for Wire Bonding"
6152	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G93-0412: "Measurement Method for Solder Sphere Size for Ball Grid Array Package" with non-conforming title change to "Test Method for Solder Sphere Size for Ball Grid Array Package"
6157	Packaging 5 Year Review Task Force	Reapproval of SEMI G23-0996 (Reapproved 0811): Test Method of Inductance for Internal Traces of Semiconductor Packages
6158	Packaging 5 Year Review Task Force	Reapproval of SEMI G42-0996 (Reapproved 0811): Specification for Thermal Test Board Standardization for Measuring Junction-to-Ambient Thermal Resistance of Semiconductor Packages
6159	Packaging 5 Year Review Task Force	Reapproval of SEMI G59-94 (Reapproved 0811): Test Method for Measurement of Ionic Contamination on Leadframe Interleafing and the Contamination Transferred from the Interleafing to the Leadframes
6160	Packaging 5 Year Review Task Force	Reapproval of SEMI G60-94 (Reapproved 0811): Test Method for the Measurement of Electrostatic Properties of Semiconductor Leadframe Interleafing Materials
6161	Packaging 5 Year Review Task Force	Reapproval of SEMI G66-96 (Reapproved 0811): Test Method for the Measurement of Water Absorption Characteristics for Semiconductor Plastic Molding Compounds
6162	Packaging 5 Year Review Task Force	Reapproval of SEMI G67-0996 (Reapproved 0811): Test Method for the Measurement of Particle Generation from Sheet Materials
6163	Packaging 5 Year Review Task Force	Reapproval of SEMI G68-0996 (Reapproved 0811): Test Method for Junction-to-Case Thermal Resistance Measurements in Air Environment for Semiconductor Packages



#	SC/TF/WG	Details
6164	Packaging 5 Year Review Task Force	Reapproval of SEMI G69-0996 (Reapproved 0811): Test Method for Measurement of Adhesive Strength Between Leadframes and Molding Compounds
6165	Packaging 5 Year Review Task Force	Reapproval of SEMI G71-0996 (Reapproved 0811): Specification for Barcode Marking of Intermediate Containers for Packaging Materials
6166	Packaging 5 Year Review Task Force	Reapproval of SEMI G89-0211: Specification for Leadframe Strip Size
6153	Packaging 5 Year Review Task Force	Reapproval of SEMI G90-0811: Specification for 300 mm Wafer Coin-Stack Type Shipping Container Used for Test and Packaging Processes

Note 1: SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstsdbsal.nsf/TFOFSNARF>

**Table 7 Authorized Ballots**

#	When	TF	Details
6154	Cycle 4	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G10-96 (Reapproved 0811): “Standard Method for Mechanical Measurement of Plastic Package Leadframes” with non-conforming title change to “Test Method for Mechanical Measurement of Plastic Package Leadframes”
6148	Cycle 4	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G18-96 (Reapproved 0811) “Standard for Integrated Circuit Leadframe Material Used in the Production of Etched Leadframes” with non-conforming title change to “Specification for Integrated Circuit Leadframe Material Used in the Production of Etched Leadframes”
6149	Cycle 4	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G38-0996 (Reapproved 0811) “Test Method for Still- and Forced-Air Junction-to-Ambient Thermal Resistance Measurements of Integrated Circuit Packages”
6150	Cycle 4	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G56-93 (Reapproved 0811) “Test Method for Measurement of Silver Plating Thickness”
6155	Cycle 4	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G62-95 (Reapproved 0811) “Test Method for Silver Plating Quality”
6151	Cycle 4	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G65-96 (Reapproved 0811) “Test Method for Evaluation of Leadframe Materials Used for L-Leaded (Gull Wing Type) Packages”
6156	Cycle 4	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G70-0996 (Reapproved 0811) “Standard for Equipment and Leadframe Fixtures for Measurement of Plastic Package Leadframes” with non-conforming title change to “Specification for Equipment and Leadframe Fixtures for Measurement of Plastic Package Leadframes”
6167	Cycle 4	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G73-0997 (Reapproved 0811) “Test Method for Pull Strength for Wire Bonding”
6152	Cycle 4	Packaging 5 Year Review Task Force	Line Item Revision to SEMI G93-0412: “Measurement Method for Solder Sphere Size for Ball Grid Array Package” with non-conforming title change to “Test Method for Solder Sphere Size for Ball Grid Array Package”
6157	Cycle 4	Packaging 5 Year Review Task Force	Reapproval of SEMI G23-0996 (Reapproved 0811): Test Method of Inductance for Internal Traces of Semiconductor Packages
6158	Cycle 4	Packaging 5 Year Review Task Force	Reapproval of SEMI G42-0996 (Reapproved 0811): Specification for Thermal Test Board Standardization for Measuring Junction-to-Ambient Thermal Resistance of Semiconductor Packages



**Table 7 Authorized Ballots**

#	When	TF	Details
6159	Cycle 4	Packaging 5 Year Review Task Force	Reapproval of SEMI G59-94 (Reapproved 0811): Test Method for Measurement of Ionic Contamination on Leadframe Interleafing and the Contamination Transferred from the Interleafing to the Leadframes
6160	Cycle 4	Packaging 5 Year Review Task Force	Reapproval of SEMI G60-94 (Reapproved 0811): Test Method for the Measurement of Electrostatic Properties of Semiconductor Leadframe Interleafing Materials
6161	Cycle 4	Packaging 5 Year Review Task Force	Reapproval of SEMI G66-96 (Reapproved 0811): Test Method for the Measurement of Water Absorption Characteristics for Semiconductor Plastic Molding Compounds
6162	Cycle 4	Packaging 5 Year Review Task Force	Reapproval of SEMI G67-0996 (Reapproved 0811): Test Method for the Measurement of Particle Generation from Sheet Materials
6163	Cycle 4	Packaging 5 Year Review Task Force	Reapproval of SEMI G68-0996 (Reapproved 0811): Test Method for Junction-to-Case Thermal Resistance Measurements in Air Environment for Semiconductor Packages
6164	Cycle 4	Packaging 5 Year Review Task Force	Reapproval of SEMI G69-0996 (Reapproved 0811): Test Method for Measurement of Adhesive Strength Between Leadframes and Molding Compounds
6165	Cycle 4	Packaging 5 Year Review Task Force	Reapproval of SEMI G71-0996 (Reapproved 0811): Specification for Barcode Marking of Intermediate Containers for Packaging Materials
6166	Cycle 4	Packaging 5 Year Review Task Force	Reapproval of SEMI G89-0211: Specification for Leadframe Strip Size
6153	Cycle 4	Packaging 5 Year Review Task Force	Reapproval of SEMI G90-0811: Specification for 300 mm Wafer Coin-Stack Type Shipping Container Used for Test and Packaging Processes



**Table 8 SNARF(s) Granted a One-Year Extension**

#	TF	Title	Expiration Date
None			

**Table 9 SNARF(s) Abolished**

#	TF	Title
None		

**Table 10 Standard(s) to receive Inactive Status**

Standard Designation	Title
SEMI G8-94 (Reapproved 0811)	Test Method for Gold Plating
SEMI G19-0997 (Reapproved 0811)	Specification for Dip Leadframes Produced by Etching
SEMI G30-88 (Reapproved 0811)	Test Method for Junction-to-Case Thermal Resistance Measurements of Ceramic Packages
SEMI G32-94 (Reapproved 0811)	Guideline for Unencapsulated Thermal Test Chip
SEMI G58-94 (Reapproved 0811)	Specification for Cerquad Package Constructions

**Table 11 New Action Items**

Item #	Assigned to	Details
None		

**Table 12 Previous Meeting Action Items**

Item #	Assigned to	Details
20161018-01	Sumio Masuchi (DISCO)	To ask the members concerned for comments and to have a conclusion of the task force, whether or not it does not have further activity. => <b>CLOSE</b>
20161018-02	Kazunori Kato (AiT)	To ask SPI TF for comments to standardize the criteria for lead-free and halogen-free descriptions on revising the published Standards => <b>OPEN</b>
20161018-03	The members on the list, Masahiro Tsuruya (iNEMI), Kazunori Kato (AiT) and Noboru Hayasaka (TOWA)	(1) To ask proper parties for reviewing each document, to be revised, reapproved, withdrawn or inactivated and (2) to get reply from them by the end of 2016. => <b>Partially OPEN</b>



## 1 Welcome, Reminders, and Introductions

Masahiro Tsuruya (iNEMI) called the meeting to order at 15:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

**Attachment:** 01\_Required\_Elements\_Reg\_20150327\_E+J

## 2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

**Motion:** To approve the minutes of the previous meeting as written.

**By / 2<sup>nd</sup>:** Kazunori Kato (AiT) / Mamoru Takahashi (Asahi Glass)

**Discussion:** None

**Vote:** 6 in favor and 0 opposed. **Motion passed.**

## 3 Technical Committee Award

The Assembly & Packaging Japan TC Chapter gave the Technical Committee Award for 2016 to Haruo Shimamoto (AIST) and Hideki Suzuki (Shin-Etsu Polymer) for their dedication to the Assembly & Packaging Technical Committee activities as task force leaders of Thin Chip Handling TF.

## 4 Liaison Reports

### 4.1 SEMI Staff Report

Chie Yanagisawa (SEMI Japan) gave the SEMI Staff Report. Of note:

- SEMI Global 2017 Calendar of Events
- 2016 SEMI Standards Excellence Award
- Global Standards Meeting Schedule
- 2017 Critical Dates for SEMI Standards Ballots
- A&R Ballot Review
- SEMI Standards Publications
- JRSC Topics
- Standards articles of SEMI Japan mail magazine
- Staff update

**Attachment:** 02\_SEMI Staff Report 20170313

## 5 Ballot Review

None



## 6 Subcommittee and Task Force Reports

### 6.1 GCS

No GCS voting was made between the previous TC Chapter meeting and this meeting.

### 6.2 Thin Chip Handling Task Force

Hideki Suzuki (Shin-Etsu Polymer) reported for the Thin Chip Handling Task Force that there is no major update. However, he continued as follows.

- The task force is working on Doc. 5836: New Standard: Test Method for Adhesive Strength for Adhesive Tray Used for Thin Chip Handling.
- SEMI G97 “Specification for Adhesive Tray Used for Thin Chip Handling” was introduced to some equipment manufacturers. One of their feedback was to suggest using carrier (and reel) for thin chip handling. They also commented that SEMI G97 could be applied for the application of MEMS or optical lens.

### 6.3 Packaging 5 Year Review Task Force

Kazuhori Kato (AiT) and Masahiro Tsuriya (iNeMI) reported that the documents published in 2011 have been reviewed and to make proposals for Revision, Reapproval or inactivating. They said the TF Should consider the documents in 2012. Details are explained at the “Old Business” section of this meeting.

### 6.4 Fiducial Mark Interoperability Task Force

Sumio Masuchi (DISCO) reported the status of this task force as follow.

- The discussion on the disbandment was made with the other task force leaders under the other TCs (PIC, I&C, Silicon Wafers and Traceability). He proposes to disband this task force. The Silicon Wafers Japan TC Chapter decided to disband the TF the Silicon Wafers Japan TC Chapter meeting on March 10, 2017.
- It was suggested to reform the TF when standard is required if a fiducial mark is disappeared by background process.

### 6.5 450 mm Assembly & Test Die Preparation (ATDP) Task Force

Sumio Masuchi (DISCO) reported that it was no progress for the 450 mm Assembly & Test Die Preparation (ATDP) Task Force.

## 7 Old Business

### 7.1 5 Year Review Check

#### 7.1.1 To standardize the criteria for lead-free and halogen-free descriptions when revising the published Standards

Kazunori Kato (AiT) said that the action item from the previous meeting is to ask SPI TF for comments to standardize the criteria for lead-free and halogen-free descriptions when revising the published Standards. However there has been no SPI TF meeting held since the previous TC Chapter meeting on October 18, 2016, so he said there was no progress.

#### 7.1.2 Review of Documents published in 2012 and before

Kazunori Kato (AiT) mentioned that proposals for Standards published in 2011 are made at the “New Business” section of this meeting.



Masahiro Tsuruya (iNEMI) said that the following three documents are proposed as Reapproval ballots.

- SEMI G83-0912: Specification for Bar Code Marking of Product Packages
  - Note that SEMI G83-0912 is updated with no technical revision when SEMI G83.1 is published in 0912 publication cycle.
- SEMI G83.1-0912: Specification for Bar Code Marking of Product Packages
  - Note that both SEMI G83 and SEMI G83.1 cover all required sections per Regulations. Both of them have same titles, purposes and scopes, but different requirements.
  - Same titles may cause confusion. If they are revised other than the title, they could be line item revisions.
- SEMI G93-0412: Measurement Method for Solder Sphere Size for Ball Grid Array Package
  - Per Appendix 4 of Procedure Manual (PM), this title should be revised as a line item revision due to nonconforming title if the title is changed to “Test Method”, which the PM recommends.

## 8 New Business

### 8.1 Proposal for New SNARFs and Ballot Submission of documents published in 2011

#### 8.1.1 Reapproval

Kazunori Kato (AiT) proposed below twelve SNARFs for reapproval.

- SEMI G23-0996 (Reapproved 0811): Test Method of Inductance for Internal Traces of Semiconductor Packages
- SEMI G42-0996 (Reapproved 0811): Specification for Thermal Test Board Standardization for Measuring Junction-to-Ambient Thermal Resistance of Semiconductor Packages
- SEMI G59-94 (Reapproved 0811): Test Method for Measurement of Ionic Contamination on Leadframe Interleafing and the Contamination Transferred from the Interleafing to the Leadframes
- SEMI G60-94 (Reapproved 0811): Test Method for the Measurement of Electrostatic Properties of Semiconductor Leadframe Interleafing Materials
- SEMI G66-96 (Reapproved 0811): Test Method for the Measurement of Water Absorption Characteristics for Semiconductor Plastic Molding Compounds
- SEMI G67-0996 (Reapproved 0811): Test Method for the Measurement of Particle Generation from Sheet Materials
- SEMI G68-0996 (Reapproved 0811): Test Method for Junction-to-Case Thermal Resistance Measurements in Air Environment for Semiconductor Packages
- SEMI G69-0996 (Reapproved 0811): Test Method for Measurement of Adhesive Strength Between Leadframes and Molding Compounds
- SEMI G71-0996 (Reapproved 0811): Specification for Barcode Marking of Intermediate Containers for Packaging Materials
- SEMI G89-0211: Specification for Leadframe Strip Size
- SEMI G90-0811: Specification for 300 mm Wafer Coin-Stack Type Shipping Container Used for Test and Packaging Processes

**Motion:** To approve SNARFs for Reapproval of G23, G42, G59, G60, G66, G67, G68, G69, G71, G89 and G90

**By / 2<sup>nd</sup>:** Kazunori Kato (AiT) / Haruo Shimamoto (AIST)

**Discussion:** None





**Vote:** 6 in favor and 0 opposed. **Motion passed.**

**Motion:** To approve submission to Cycle 4-2017 for ballots of Reapproval of G23, G42, G59, G60, G66, G67, G68, G69, G71, G89 and G90

**By / 2<sup>nd</sup>:** Kazunori Kato (AiT) / Haruo Shimamoto (AIST)

**Discussion:** None

**Vote:** 6 in favor and 0 opposed. **Motion passed.**

### 8.1.2 Line Item Revision

Kazunori Kato (AiT) proposed below nine SNARFs for line item revision.

- SEMI G10-96 (Reapproved 0811): Standard Method for Mechanical Measurement of Plastic Package Leadframes
- SEMI G18-96 (Reapproved 0811): Standard for Integrated Circuit Leadframe Material Used in the Production of Etched Leadframes
- SEMI G38-0996 (Reapproved 0811): Test Method for Still- and Forced-Air Junction-to-Ambient Thermal Resistance Measurements of Integrated Circuit Packages
- SEMI G56-93 (Reapproved 0811): Test Method for Measurement of Silver Plating Thickness
- SEMI G62-95 (Reapproved 0811): Test Method for Silver Plating Quality
- SEMI G65-96 (Reapproved 0811): Test Method for Evaluation of Leadframe Materials Used for L-Leaded (Gull Wing Type) Packages
- SEMI G70-0996 (Reapproved 0811): Standard for Equipment and Leadframe Fixtures for Measurement of Plastic Package Leadframes
- SEMI G73-0997 (Reapproved 0811): Test Method for Pull Strength for Wire Bonding
- SEMI G93-0412: Measurement Method for Solder Sphere Size for Ball Grid Array Package

**Motion:** To approve SNARFs for line item revision to G10, G18, G38, G56, G62, G65, G70, G73 and G93

**By / 2<sup>nd</sup>:** Kazunori Kato (AiT) / Haruo Shimamoto (AIST)

**Discussion:** None

**Vote:** 6 in favor and 0 opposed. **Motion passed.**

**Motion:** To approve submission to Cycle 4/5-2017 for ballots of Line Item Revision to G10, G18, G38, G56, G62, G65, G70, G73 and G93

**By / 2<sup>nd</sup>:** Kazunori Kato (AiT) / Haruo Shimamoto (AIST)

**Discussion:** None

**Vote:** 6 in favor and 0 opposed. **Motion passed.**

### 8.2 Proposal for inactivating documents published in 2011

Kazunori Kato (AiT) proposed below five documents for inactive.

- SEMI G8-94 (Reapproved 0811): Test Method for Gold Plating
- SEMI G19-0997 (Reapproved 0811): Specification for Dip Leadframes Produced by Etching



- SEMI G30-88 (Reapproved 0811): Test Method for Junction-to-Case Thermal Resistance Measurements of Ceramic Packages
- SEMI G32-94 (Reapproved 0811): Guideline for Unencapsulated Thermal Test Chip
- SEMI G58-94 (Reapproved 0811): Specification for Cerquad Package Constructions

**Motion:** To approve inactivating G8, G19, G30, G32 and G58  
**By / 2<sup>nd</sup>:** Kazunori Kato (AiT) / Haruo Shimamoto (AIST)  
**Discussion:** None  
**Vote:** 6 in favor and 0 opposed. **Motion passed.**

### 8.3 Proposal to disband Fiducial Mark Interoperability Task Force under the Assembly & Packaging Japan TC Chapter

Sumio Masuchi (DISCO) proposed to disband Fiducial Mark Interoperability Task Force.

**Motion:** To approve the disbandment for FMI TF under the Assembly & Packaging Japan TC Chapter  
**By / 2<sup>nd</sup>:** Sumio Matuschi (DISCO) / Kiyotaka Chiba (Tokyo Seimitsu)  
**Discussion:** None  
**Vote:** 5 in favor and 0 opposed. **Motion passed.**

### 8.4 Discussion to integrate 3DS-IC TC into one new TC.

Masahiro Tsuruya (iNEMI) explained the status of this discussion as attached material. The proposal of this integration will be submitted for approval at ISC meeting during SEMICON West.

**Attachment:** 03\_New Charter Proposal\_ver1

## 9 Next Meeting and Adjournment

The next meeting is scheduled for Monday, July 24, 2017 at SEMI Japan office, Tokyo, Japan. See <http://www.semi.org/en/events> for the current list of meeting schedules.

At the end of the meeting, Masahiro Tsuruya (iNEMI) mentioned that he will make some interviews for standardization for copper wire for future discussion.

Having no further business, a motion was made to adjourn. Adjournment was at 17:00.



Respectfully submitted by:

Chie Yanagisawa

Manager

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Minutes tentatively approved by:

Kazunori Kato (AiT), Co-chair	July 23, 2017
Masahiro Tsuruya (iNEMI), Co-chair	July 23, 2017

**Table 13 Index of Available Attachments<sup>#1</sup>**

<i>Title</i>	<i>Title</i>
01_Required_Elements_Reg_20150327_E+J	03_New Charter Proposal_ver1
02_SEMI Staff Report 20170313	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at [www.semi.org](http://www.semi.org). For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.